

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
)
Keiichi SASAKI et al.) Parent Group Art Unit: 2823
)
1.53(b) Divisional of U.S. Appl. No.) Parent Examiner: W. Brewster
09/722,467, filed November 28, 2000)
)
Filed: Herewith)
)
For: PASTE INCLUDING A MIXTURE)
OF POWDERS, CONNECTION)
PLUG, BURYING METHOD, AND)
SEMICONDUCTOR DEVICE)
MANUFACTURING METHOD)
(AS AMENDED))

Mail Stop Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

PRELIMINARY AMENDMENT

Prior to the examination of the above-identified application, please amend
this application as follows:

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TITLE

Please replace the title of this application with the following:

PASTE INCLUDING A MIXTURE OF POWDERS, CONNECTION PLUG,
BURYING METHOD, AND SEMICONDUCTOR DEVICE MANUFACTURING
METHOD

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